in a second working step, activating at least one region of the lower insulating layer; and

in a third working step, applying at least one upper insulating layer having a layer thickness between 0.05 µm and 50 µm and being chemically different from said at least one lower insulating layer to the lower, activated insulating layer and patterning the at least one upper insulating layer.

25. The process according to claim 24, which comprises patterning the lower insulating layer in the first working step.

26. The process according to claim 24, which comprises choosing a selected layer from the group consisting of the at least upper one insulating layer and the lower insulating layer and patterning the selected layer after the selected layer has been applied.

27. A process for producing a component, which comprises:

in a first working step, applying a first insulating layer having a layer thickness between 0.05 µm and 50 0.05 µm to a substrate;

in a second working step, applying a second insulating layer having a layer thickness between 0.05 µm and 50 µm and being chemically different from said at least one lower insulating layer and patterning the second insulating layer; and

in a third working step, activating a layer selected from the group consisting of the first insulating layer and the second insulating layer.

28. The process according to claim 27, which comprises patterning the first insulating layer in the first working step.

29. The process according to claim 27, which comprises patterning the second insulating layer after the second working step and before the third working step.

30. The process according to claim 29, which comprises patterning the lower insulating layer, after the first working step.

31. The process according to claim 27, which comprises patterning the lower insulating layer, after the first working step.